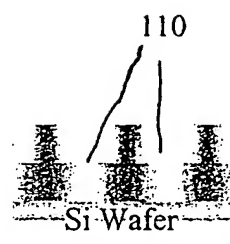
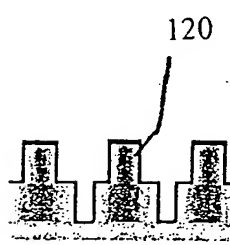


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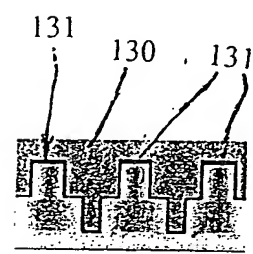
(a)

Low k Dielectric  
Material patterned



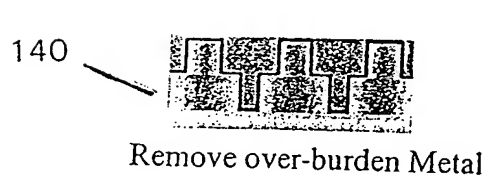
(b)

Diffusion Barrier  
(Ti, Ta, TaN)

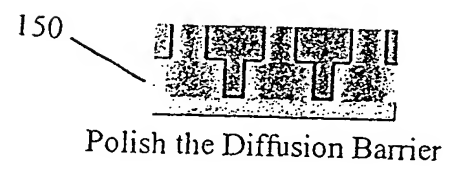


(c)

Cu



(d)



(e)

FIG. 1

200

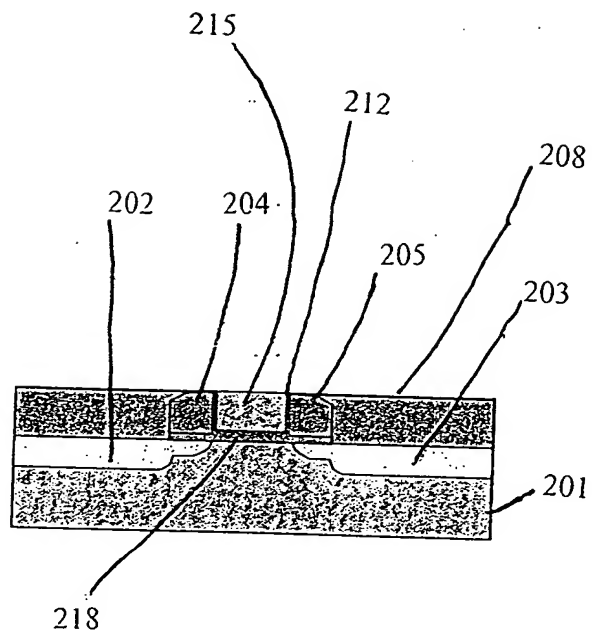


FIG. 2

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300

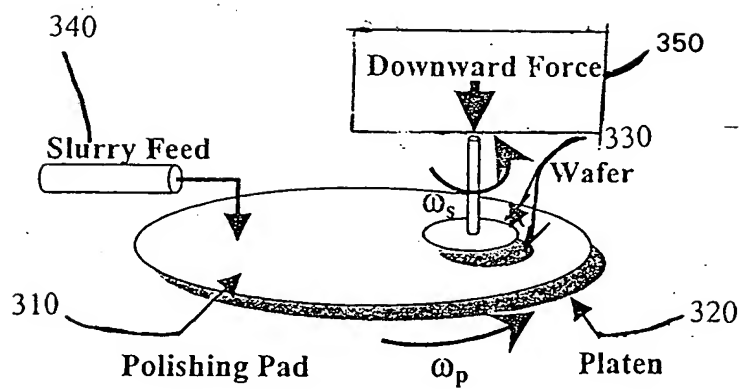


FIG. 3

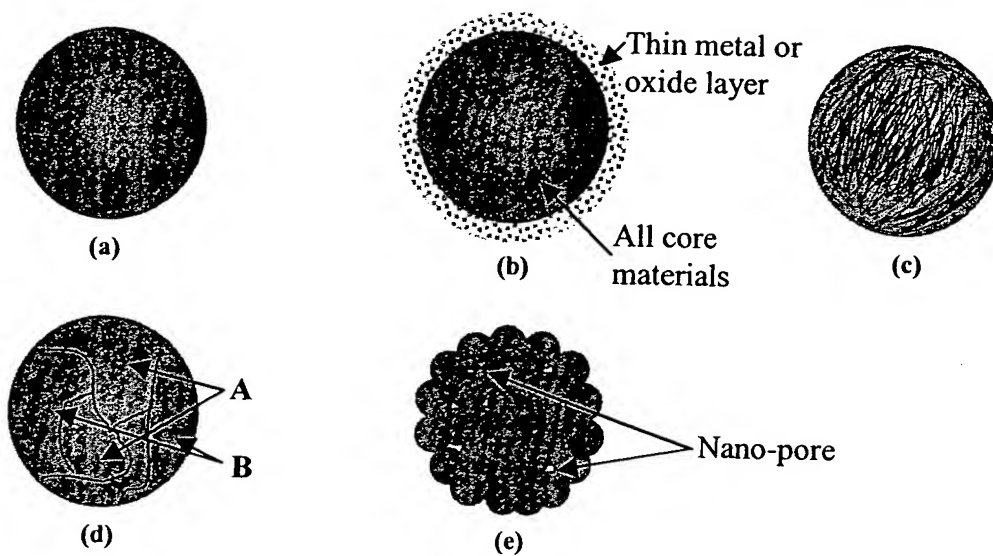


FIG. 4

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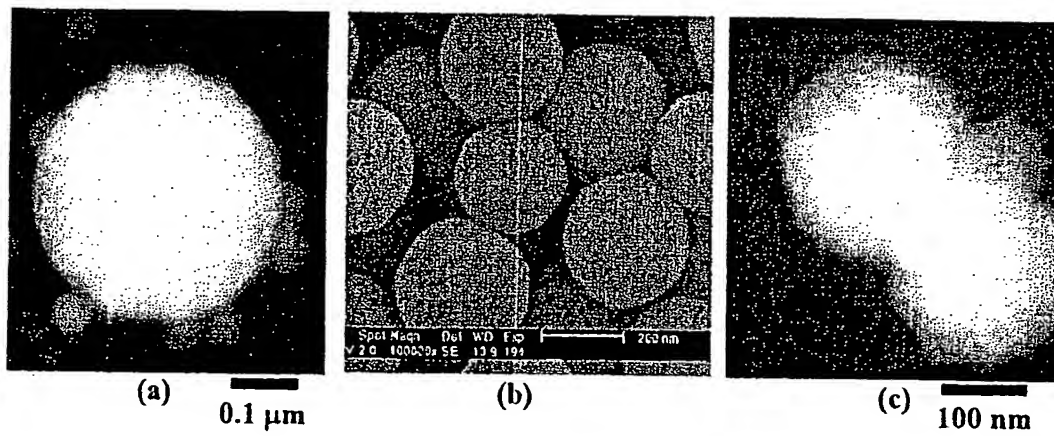


FIG. 5

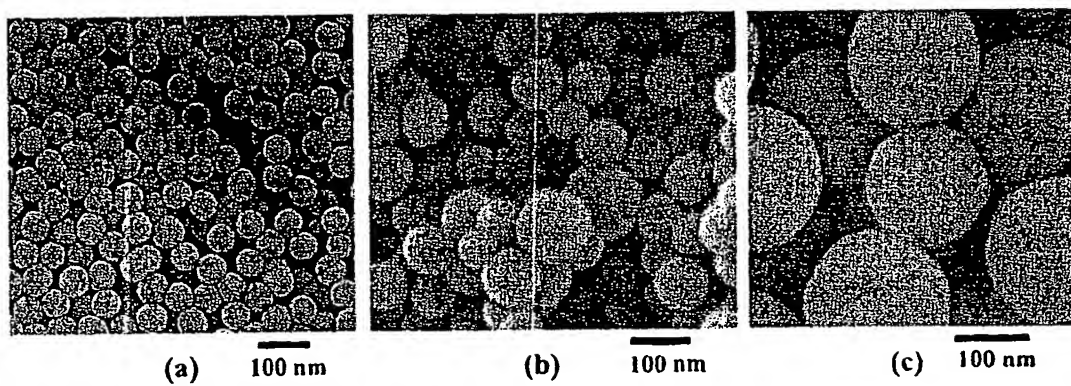
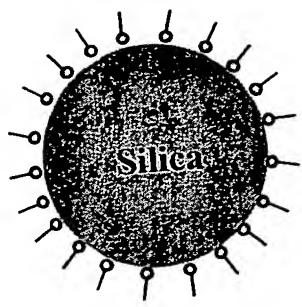
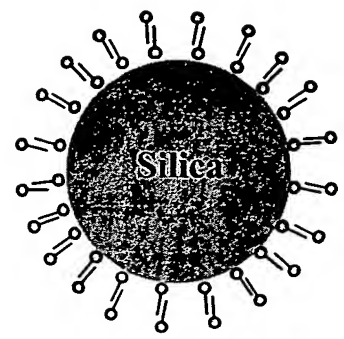


FIG. 6

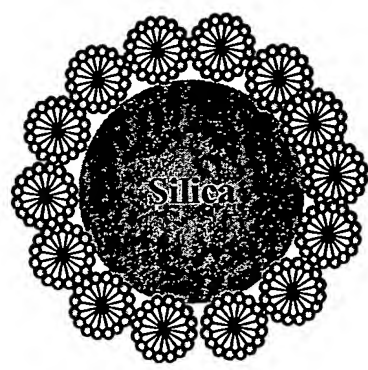
202220-01028001



(a)



(b)



(c)



Tantalum



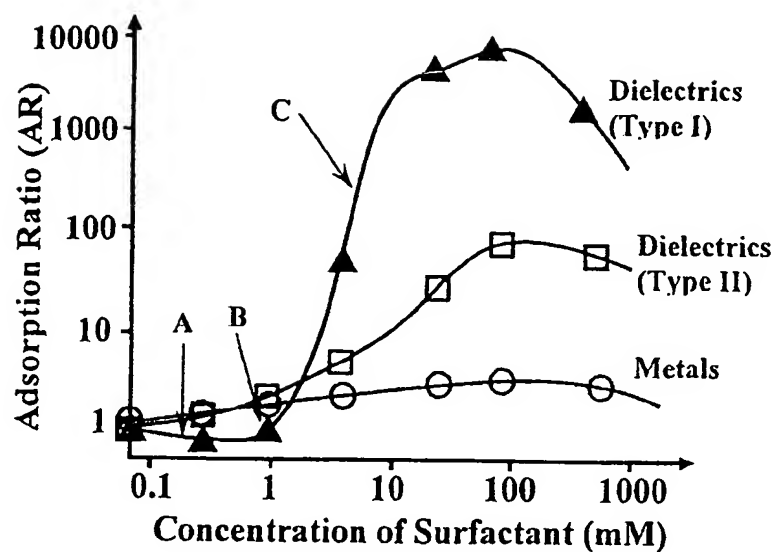
Copper



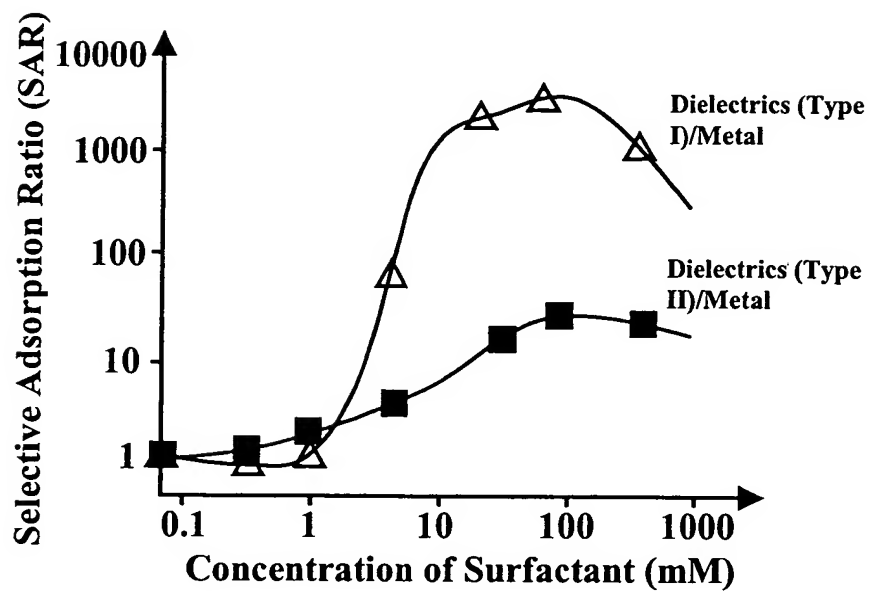
SiO<sub>2</sub>

(d)

FIG. 7



(a)



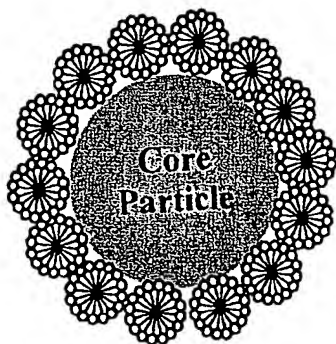
(b)

FIG. 8

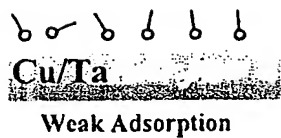


2022220-01028001

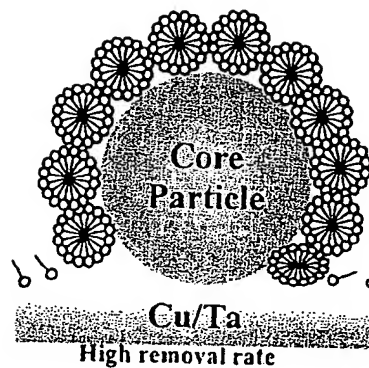
(a)



(b)



Pressure



(c)



Pressure

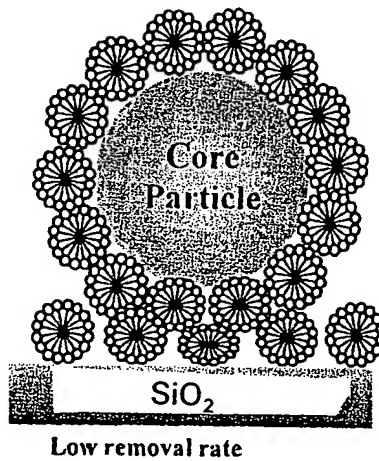


FIG. 9

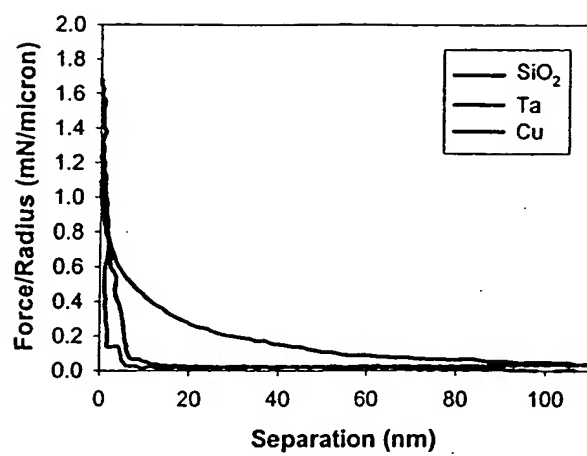


FIG. 10

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